

PART INFORMATION	
Mfg Item Number	AFT09MS007NT1
Mfg Item Name	PLD-1.5W
SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2018-04-18
Response Document ID	00E1K03942D004A1.12
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com
DECLARATION	
EU RoHS	Yes
Pb Free	No
HalogenFree	Yes
Plating Indicator	e3
EU RoHS Exemption(s)	7a
MANUFACTURING	
Mfg Item Number	AFT09MS007NT1
Mfg Item Name	PLD-1.5W
Version	ALL
Weight	0.280000
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	<p>Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.</p>
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7a:Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart	SubPart%	ARTICLEPPM	ARTICLE%
Solder Die Attach	0.0152	Lead/Lead Compounds	Lead	7439-92-1	7a	g	955000	95.5		51942	5.1842
Solder Die Attach		Metals	Silver, metal	7440-22-4		g	25000	2.5		1357	0.1357
Solder Die Attach		Metals	Tin, metal	7440-31-5		g	20000	2		1085	0.1085
Bonding Wire	0.0024	Metals	Gold, metal	7440-57-5		g	1000000	100		8571	0.8571
Bonding Wire		Metals				g				1	0.0001
Lead Frame Plating	0.002	Lead/Lead Compounds	Lead	7439-92-1		g	200	0.02		7141	0.7141
Lead Frame Plating		Metals	Tin, metal	7440-31-5		g	999800	99.98		27369	2.7369
Die Encapsulant	0.1024	Solvents, additives, and other materials	Benzophenonetetracarboxylic Acid Dianhydride	2421-28-5		g	74838	7.4838		10947	1.0947
Die Encapsulant		Plastics/polymers	Poly[(o-cresyl glycidyl ether)-co-formaldehyde]	29690-82-2		g	29935	2.9935		10947	1.0947
Die Encapsulant		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		g	29935	2.9935		652	0.6652
Die Encapsulant		Metals	Magnesium, metal	7439-95-4		g	1785	0.1785		1960	0.196
Die Encapsulant		Solvents, additives, and other materials	Other organic Silicon Compounds	-		g	5361	0.5361		291941	29.1941
Die Encapsulant		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		g	29935	2.9935		10947	1.0947
Die Encapsulant		Glass	Silica, vitreous	60976-86-0		g	798276	79.8276		337991	33.7991
Die Encapsulant		Plastics/polymers	Poly[(phenyl glycidyl ether)-co-dicyclopentadiene]	119345-05-0		g	29935	2.9935		209875	20.9875
Silicon Semiconductor Die	0.0046	Metals	Gold, metal	7440-57-5		g	10200	1.02		167	0.0167
Silicon Semiconductor Die		Metals				g				325	0.0325
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		g	19796	1.9796		15935	1.5935
Silicon Semiconductor Die		Glass	Silicon, doped	-		g	970004	97.0004			
Copper Lead Frame, Ni spot	0.1534	Metals	Copper, metal	7440-50-8		g	616915	61.6915			
Copper Lead Frame, Ni spot		Solvents, additives, and other materials	Potassium silver cyanide	506-61-6		g	383085	38.3085			

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/AFT09MS007NT1_IPC1752_v11.xml

http://www.freescale.com/mcds/AFT09MS007NT1_IPC1752A.xml